MT53D1024M32D4DT-053 AAT

Orderable parts
MT53D1024M32D4DT-053 AAT:D

Specs

Chipset Validation	N/A
Cycle Time	
Data Rate	DDR4-3732
Density	32Gb
FBGA Code	D9WPS
Op. Temp.	-40C to +105C
Part Status	Production
Product Longevity Program	No
Product Longevity Program Start Date	N/A
Technology	LPDDR4
Width	x32

RoHS

China RoHS Certificate

Part-specific certification as required by China's Management Methods for Controlling Pollution by Electronic Information Products.

- File Type: (PDF)
- Updated: 8/1/2022

Download

RoHS Certificate of Compliance

Part-specific certification of how this product meets the requirements of the current DIRECTIVE 2011/65/EU and 2015/863/EU, a.k.a. Restriction of Hazardous Substances (RoHS) Directive (Recast) without exemptions.

- File Type: (PDF)
- Updated: 8/1/2022

Download

REACH Statement

Company statement regarding REACH SVHC compliance

- File Type: (PDF)
- Updated: 8/1/2022

Download

Simulation Models

HSPICE: 8Gb Mobile LPDDR4 Z11M

WT, UT, AT, IT, Z11M Mobile LPDDR4 SDRAM, Die Rev. D, 556b, 432b, 376b, 366b, 200b

- File Type: ZIP
- Updated: 2020-10-06

Download

IBIS: 8Gb Mobile LPDDR4 Z11M

WT, UT, AT, IT, Z11M Mobile LPDDR4 SDRAM, Die Rev. D, 556b, 432b, 376b, 366b, 200b

- File Type: ZIP
- Updated: 2020-10-06

Download

Technical Notes

TN-00-08: Thermal Applications

This tech note describes considerations in thermal applications for Micron memory devices, including thermal impedance, thermal resistance, junction temperature, operating temperature, memory reliability, reliability modeling, device reliability, and high-temperature electronics.

- File Type: PDF
- Updated: 2021-11-16

Download

TN-00-14: Understanding Quality and Reliability Requirements for Bare Die Applications

This technical note describes the quality and reliability requirements for bare die applications.

- File Type: PDF
- Updated: 2009-10-15

Download

See All

Customer Service Notes

CSN-16: Micron Component and Module Packaging

Explanation of Micron packaging labels and procedures.

- File Type: PDF

- Updated: 2021-12-06

Download

CSN-24: ESD Precautions for Die/Wafer Handling and Assembly

Describes the benefits of controlling ESD in the workplace, including higher yields and improved quality and reliability, resulting in reduced manufacturing costs.

- File Type: PDF
- Updated: 2010-08-05

Download